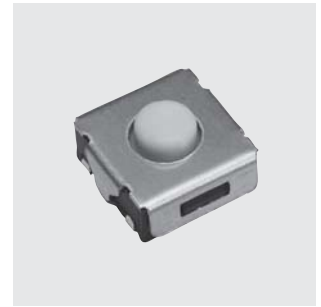


SMT3/SMTE3

Surface Mount Tactile Switches

Washable

RoHS Compliant



■ Features

- 1. Compatible With Lead-Free, Reflow Soldering**
Heat-resistance resin for lead-free soldering.
- 2. Washable (SMTE3 Series)**
- 3. J-Lead Terminal Pins For High-Density Mounting**
- 4. Anti-Static Electricity (SMTE3 Series)**
Ground terminal is provided to prevent damage to element caused by static electricity.

■ Specifications

Rating	Max.	0.6VA max. (24VDC max. 30mA max.)	
	Min.	Silver plated contacts	1mA DC5V
		Gold plated contacts	10μA DC5V
Initial contact resistance		100m Ω max. (1.5mA 200μVAC)	
Dielectric strength		250VAC 1 minute	
Insulation resistance		100M Ω min. (100VDC)	
Electrostatic capacity		5pF max.	
Electrical life		100,000 operations	
Stroke	SMT3	0.25mm	
	SMTE3	0.5mm	
Operating force	SMT3	1.18±0.39 N	
	SMTE3	1.96±0.98 N	
Operating temperature range		-25~+70°C	
Storage temperature range		-40~+85°C	

■ Part Numbering

SMT E G 3 - 01 E - Z

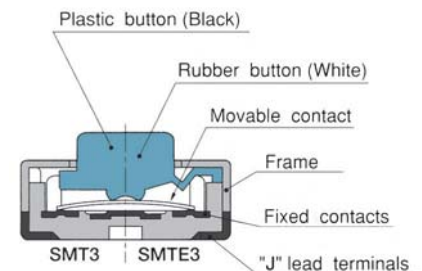
Series code Structure Contact plating Series No. Registration No. Packaging specs.

None	Standard type (Plastic button)
E	Immersion washable (Rubber button)

None	Silver plated
G	Gold plated

None	Stick
E	Emboss taping

■ Structure



■ Table of Part Numbers

Structure	Packaging specifications	
	Stick	Emboss taping
Standard type	SMT3-01-Z	SMT3-01E-Z ★ SMTG3-01E-Z
Immersion washable	SMTE3-01-Z ★ SMTEG3-01-Z	SMTE3-01E-Z ★ SMTEG3-01E-Z

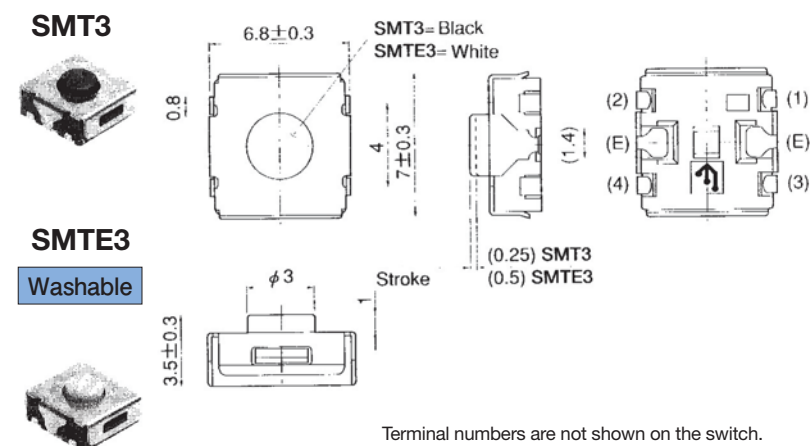
■ Pad Layouts

(Top view)

Ground terminals	Without	With
Part No.	SMT3 · SMTE3 SMTG3 · SMTEG3	SMTE3 SMTEG3
Pattern dimensions		

SMT3

SPST



Part No.	Switching function	
SMT3-01-Z SMT3-01E-Z SMTEG3-01E-Z SMTE3-01-Z SMTE3-01E-Z SMTEG3-01-Z SMTEG3-01E-Z	OFF	(ON)
Connecting terminals	—	1 — 3 2 — 4
Circuit diagrams		

(ON) : Momentary

(E) : GGround terminal (SMTE3 and SMTEG3 series)

Soldering Specifications

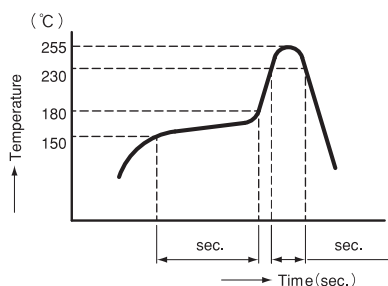
(1) Manual Soldering

Device : Soldering iron

① 350°C ± 10°C; 3 ± 0.5 seconds

(2) Reflow Soldering

Device : Inline or batch system



Apply reflow soldering up to 2 times max.

Flux Cleaning

Since the **SMT3** series is not process sealed, be sure to use low-residue flux.

(1) Solvent: Fluorine or Alcohol type

Cleaning with other solvents or water is not possible.

(2) Cleaning after soldering should be done after the terminal temperature falls to 90°C or below, or after leaving the switch for five minutes or longer at room temperature.

Cleaning temperature: 43°C, max.

(3) Do not use ultrasonic cleaning.

Packaging Specifications

Stick	Emboss taping
<p>50 pcs/stick</p> <p>φ=375</p>	<p>1,000 pcs/reel</p> <p>Top cover tape</p> <p>Emboss carrier tape</p>

● When ordering, tape packaged version shall be supplied by request. Minimum packaging quantity for reel packaging is 1,000pcs per reel.

(ON) : Momentary